

TURNEY DOCKET NO.: AGX-37  
 IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

O I P E  
 JCSA  
 2001  
 In re Application of: Shooshtarian, et al.  
 Serial No. 327,873

Filed: March 17, 2000 ) Group Art Unit: 2823  
 Confirmation No.: 4182 ) Examiner: Hsein-Ming Lee  
 Title: Localized Heating and Cooling of Substrates )  
 Our Account No.: 04-1403

Commissioner for Patents  
 U.S. Patent and Trademark Office  
 Washington, DC 20231

**AMENDMENT AFTER FINAL**

This is a response/amendment/letter in the above-identified application and includes the herewith attachment of same date and subject which is incorporated herein by reference and the signature below is to be treated as the signature to the attachment in absence of a signature thereto.

Fee requirements (if any) have been calculated as shown below:

Claims remaining after amendment	Highest number previously paid for	Present Extra	Additional Fee
Total Effective Claims	minus	=	x \$18 = \$

Independent Claims minus = x \$80 = \$

If amendment enters proper multiple dependent claim(s) into this application for first time, add \$270.00 (per application) \$

Since Official Action set an original due date of \_\_\_\_\_ \$

PETITION is hereby made for an extension to cover the date this response is filed for which the requisite fee is enclosed (1 month \$110; 2 months \$390; 3 months \$890; 4 months \$1390) \$

If Terminal Disclaimer enclosed, add Rule 20(d) Official Fee (\$110.00) \$

**SUBTOTAL:** \$

If "small entity" verified statement filed [ ] previously,  
 [ ] herewith, enter one-half ( $\frac{1}{2}$ ) of subtotal and subtract \$

**TOTAL:** \$

Other: Appendix A \$

**TOTAL FEE ENCLOSED:** \$

The Commissioner is hereby authorized to charge any fee specifically authorized hereafter, or any fees in addition to the fee(s) filed, or asserted to be filed, or which should have been filed herewith or concerning any paper filed hereafter, and which may be required under Rules 16-18 (deficiency only) now or hereafter relative to this application and the resulting official document under Rule 20, or credit any overpayment, to our Account No. shown in the heading hereof for which purpose a duplicate copy of this sheet is attached. This statement does not authorize charge of the issue fee in this case.

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DORITY & MANNING  
 ATTORNEYS AT LAW, P.A.  
 By Atty: Jason W. Johnston Reg. No.: 45,675

Signature: J.W. Johnston

hereby certify that this correspondence and any referenced attachment and fee are being deposited with the United States Postal Service as first class mail in an envelope addressed to: Commissioner for Patents, U.S. Patent and Trademark Office, Washington, DC 20231, on September 17, 2001.

Lynn Watkins  
 Typed or printed name of person mailing paper or fee)  
Lynn Watkins  
 Signature of person mailing paper or fee)



AF/2823

**PATENT**  
ATTORNEY DOCKET NO.: AGX-37

## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

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Shooshtarian, et al.    )  
Serial No.: 09/527,873    )  
Filed: March 17, 2000    )  
Title: Localized Heating and    )  
Cooling of Substrates    )

Examiner: Hsein-Ming Lee  
Art Unit: 2823  
Dept. Acct. No.: 04-1403

Commissioner for Patents  
Washington, D.C. 20231

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TECHNOLOGY CENTER 2800

#13/Jonell C  
Caren  
A. faced  
9/21/01**AMENDMENT AFTER FINAL**

Dear Sir:

In response to the Office Action dated July 18, 2001, please amend the above-captioned application as follows:

**IN THE CLAIMS**

Please amend claim 1 to read as follows (See also Appendix A):

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9/27/01  
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- 
1. (Twice Amended) A method for heat treating a semiconductor wafer, said method comprising the steps of:  
    placing a semiconductor wafer in a thermal processing chamber that is in communication with a plurality of lamps, said semiconductor wafer defining a plurality of localized regions along a radial axis;  
    adjusting the temperature of said semiconductor wafer to a predetermined temperature according to a predetermined heat cycle, said predetermined heat cycle